

## Features

- Fast Switching Speed
- Low Profile DFN Package (0.575mm typical thickness) is Much Thinner than Conventional SOT Style Packages
- Thermally Efficient DFN Package Features 500mW Power Dissipation Capability in a Compact 2.0 \* 2.0mm Footprint
- Two "BAV99" Circuits In One Package
- **Lead Free/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**

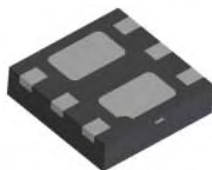
## Mechanical Data

- Case: DFN2020B-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)

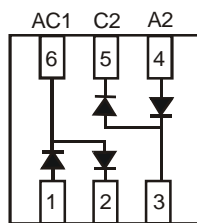
DFN2020B-6



Top View



Bottom View


 Top View  
 Internal Schematic

Pin 1 = A1 (anode 1, right below the notch indication)  
 Pin 2 = C1 (cathode 1)  
 Pin 3 = AC2 (internally connected to rectangular pad)  
 Pin 4 = A2 (anode 2)  
 Pin 5 = C2 (cathode 2)  
 Pin 6 = AC1 (internally connected to the pad with a notch)

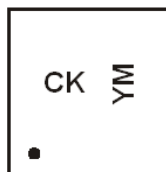
## Ordering Information (Note 3)

Part Number	Case	Packaging
BAV99BRLP-7	DFN2020B-6	3000/Tape & Reel

Notes:

1. No purposefully added lead.
2. Diodes Inc.'s "Green" policy can be found on our website at <http://www.diodes.com>.
3. For packaging details, go to our website at <http://www.diodes.com>.

## Marking Information



CK = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: Y = 2011)  
 M = Month (ex: 9 = September)

### Date Code Key

Year	2011	2012	2013	2014	2015	2016	2017
Code	Y	Z	A	B	C	D	E

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

## Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	100	V
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	75	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	53	V
Forward Continuous Current (Note 4)	I <sub>FM</sub>	300	mA
Non-Repetitive Peak Forward Surge Current	I <sub>FSM</sub>	@ t = 1.0μs	3.0
		@ t = 1.0ms	2.0
		@ t = 1.0s	0.5
			A

## Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	P <sub>D</sub>	500	mW
Thermal Resistance Junction to Ambient Air (Note 4)	R <sub>θJA</sub>	250	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	V <sub>(BR)R</sub>	75	—	V	I <sub>R</sub> = 2.5μA
Forward Voltage	V <sub>F</sub>	—	0.715	V	I <sub>F</sub> = 1.0mA
			0.855		I <sub>F</sub> = 10mA
			1.0		I <sub>F</sub> = 50mA
			1.25		I <sub>F</sub> = 150mA
Reverse Current (Note 5)	I <sub>R</sub>	—	2.5	μA	V <sub>R</sub> = 75V
			50	μA	V <sub>R</sub> = 75V, T <sub>J</sub> = 150°C
			30	μA	V <sub>R</sub> = 20V, T <sub>J</sub> = 150°C
			25	nA	V <sub>R</sub> = 20V
Total Capacitance	C <sub>T</sub>	—	2.0	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	4.0	ns	I <sub>F</sub> = I <sub>R</sub> = 10mA, I <sub>rr</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω

Notes: 4. Device mounted on FR-4 PCB, on minimum recommended, 2oz copper pad layout.  
5. Short duration pulse test used to minimize self-heating effect.

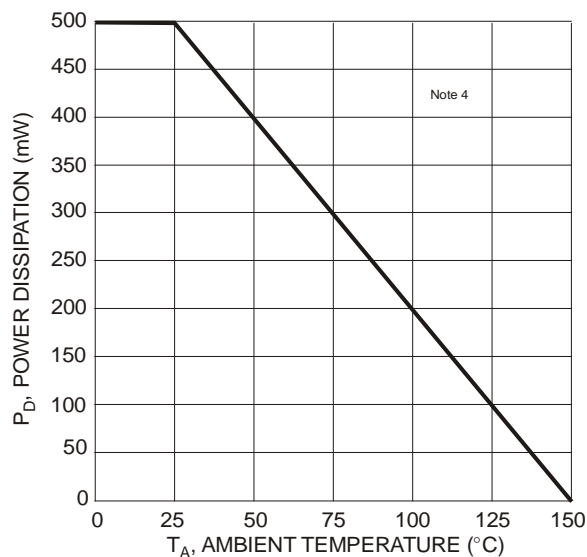


Fig. 1 Power Derating Curve, Total Package

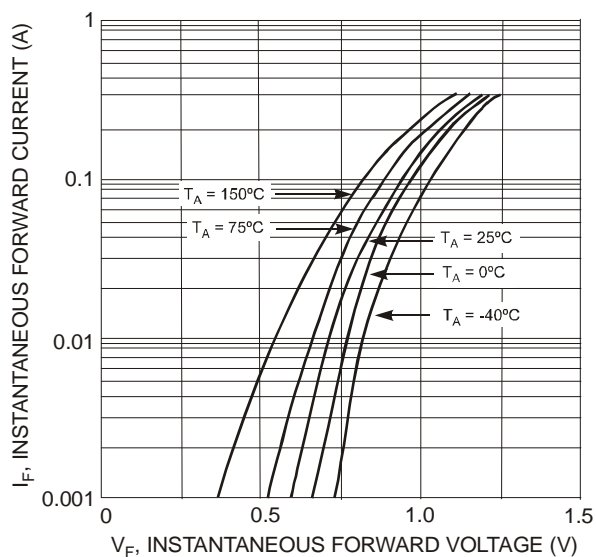


Fig. 2 Typical Forward Characteristics, Per Element

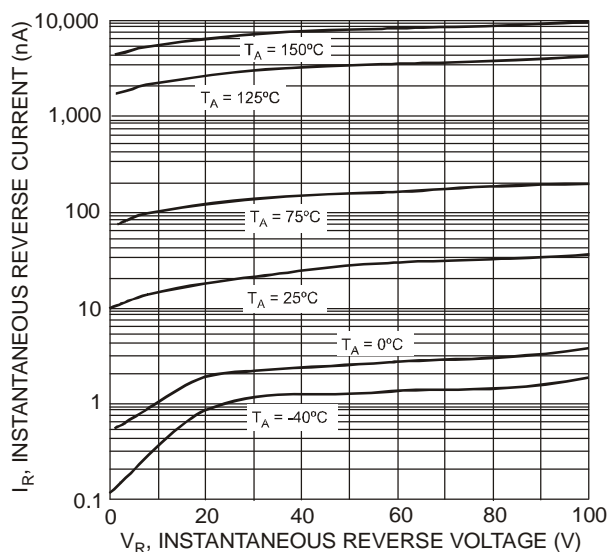


Fig. 3 Typical Reverse Characteristics, Per Element

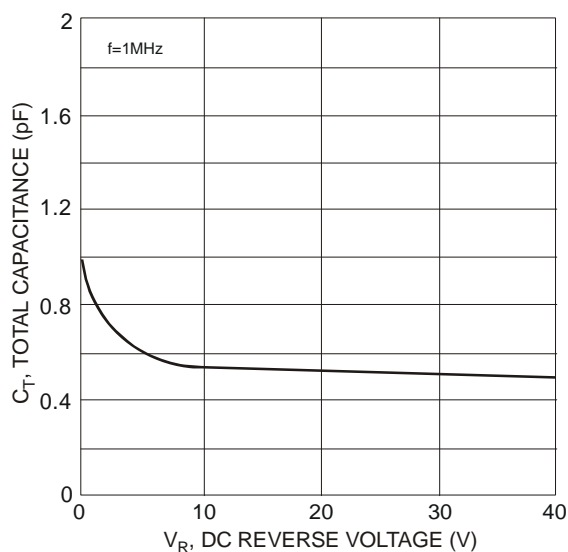
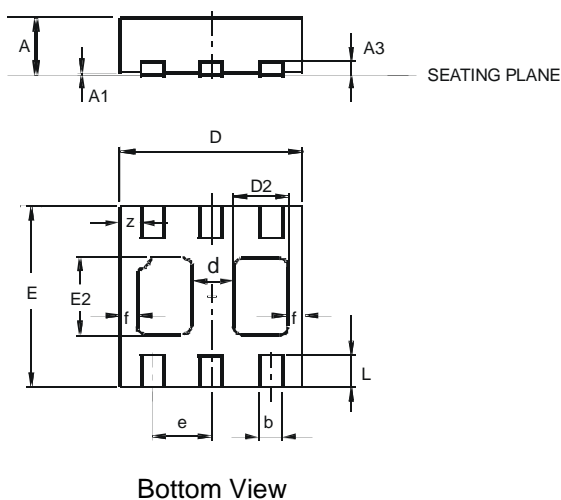


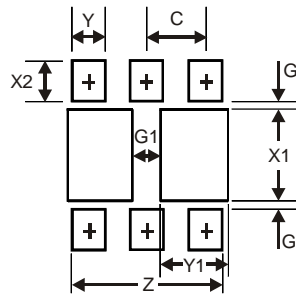
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

## Package Outline Dimensions



DFN2020B-6			
Dim	Min	Max	Typ
A	0.545	0.605	0.575
A1	0	0.05	0.02
A3	—	—	0.13
b	0.20	0.30	0.25
D	1.95	2.075	2.00
d	—	—	0.45
D2	0.50	0.70	0.60
e	—	—	0.65
E	1.95	2.075	2.00
E2	0.90	1.10	1.00
f	—	—	0.15
L	0.25	0.35	0.30
z	—	—	0.225
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Y	0.37
Y1	0.70
C	0.65

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